



Docket No.: M4065.0127/P127-A  
(PATENT)

#1814  
C88  
6/25/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Kie Y. Ahn, et al

Application No.: 09/660,324

Group Art Unit: 2581

Filed: September 12, 2000

Examiner: F. Toledo

For: SILICON MULTI-CHIP MODULE  
PACKAGING WITH INTEGRATED  
PASSIVE COMPONENTS AND METHOD  
OF MAKING

AMENDMENT

Box Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313

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JUN 18 2003  
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Dear Sir:

In response to the Office Action dated March 17, 2003 (Paper No. 16), please  
amend the above-identified U.S. patent application as follows:

In the Claims

Please cancel claim 124.

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